

IEEE COMCOMAP 2021
Shenzhen, China, Nov. 26 - 28, 2021

Welcome Message from the General Chairs



Dr. Qingfeng Zhang

IEEE COMCOMAP 2021 General Chair



Prof. Yi Gong

IEEE COMCOMAP 2021 General Chair

On behalf of the Organizing Committee of 2021 IEEE International Conference on Computing, Communications & IoT Applications (IEEE COMCOMAP 2021), it is our great pleasure to welcome each participant in Shenzhen, one of the most beautiful cities in China. The conference is held in Vienna International Hotel (Shenzhen North Station Store), from 26 (Friday) through 28 (Sunday) Nov. 2021. The event is organized by Southern University of Science and Technology under the auspices of the IEEE and the IEEE Antennas and Propagation Society- Shenzhen Chapter.

Shenzhen, a beautiful coastal city situated just across the border from Hong Kong, is a showcase of China's reforms and opening up to the rest of the world. Over years, Shenzhen has developed from a small fishing village into a modern city with a population of 17 million and a gross domestic product (GDP) ranking among the highest in China. SHENZHEN — Shenzhen, once again, is at the vanguard of China's development, harking back to more than three decades ago, when it became the nation's first special economic zone to lead the reform and opening-up.

Now the southern Chinese city is embracing a new unparalleled role as "a pilot demonstration area of socialism with Chinese characteristics." The setting of IEEE COMCOMAP 2021 in Shenzhen will enable you to explore the most recent advances and new techniques in computing, communications and IoT applications, to explore famous tourist attractions in Shenzhen, and to network with friends, colleagues, and customers from around the world.

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Greetings from the TPC Chairs



Prof. Yejun He
IEEE COMCOMAP 2021 TPC Chair



Prof. Fei Richard Yu
IEEE COMCOMAP 2021 TPC Chair

On behalf of the Technical Program Committee, We would like to welcome all the participants of the 2021 IEEE International Conference on Computing, Communications & IoT Applications (IEEE COMCOMAP 2021) . It is great honor for us to welcome researchers and scientists coming from all around the world.

ComComAp 2021's mission is to bring together innovative researchers, developers, and practitioners from academia, industry, and governments to disseminate their significant research findings and to expand their innovative research ideas. The conference received more than 102 paper submissions. All papers were rigorously and independently peer-reviewed by more than 61 Technical Program Committee (TPC) members and a large number of reviewers. The program committee had a difficult task to select 73 full papers among many high-quality submissions for presentation and publication, representing an overall acceptance rate of about 71.6%. In addition, we invited 8 renowned IEEE Fellows to deliver their keynote speeches.

The final technical program of ComComAp 2021 is the result of the devotion and hard work of many people. We would like to extend our sincere thanks to all the authors who submitted their work, the Track Chairs/Special Session Organizers/TPC members, and reviewers, who greatly contributed to the success of the ComComAp 2021 paper review process under a tight schedule, and everyone else who contributed to putting together a comprehensive and inspiring program. In particular, we would like to thank the Local Organizer, Southern University of Science and Technology, and the Sponsor, IEEE, and IEEE Antennas and Propagation Society-Shenzhen Chapter for their generous support to ComComAp 2021.

We cordially invite all of you to join us and interact with our outstanding keynote speakers and

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experts in the conference. Our goal is to make your participation in ComComAp 2021 one of the most productive and memorable experiences of your life from both professional and personal perspectives. Welcome to beautiful Shenzhen!

Prof. Yejun He

IEEE COMCOMAP 2021 TPC Chair

Prof. Fei Richard Yu

IEEE COMCOMAP 2021 TPC Chair